

3. (Amended) The electronic circuit of claim 1, wherein an etched surface of the chip faces the first surface of the base, and the chip is connected to the antenna by welding beads.

4. (Amended) The electronic circuit of claim 1, wherein an etched surface of the chip faces the back of the first surface of the base, the chip is placed in a slot made through the base, and the chip is connected to the antenna by welding beads, the chip being attached to the base by a drop of resin.

5. (Amended) The electronic circuit of claim 1, wherein an etched surface of the chip faces the back of the first surface of the base and the chip is connected to the antenna by welding beads located in connection slots going through the base, the chip being attached to the base by a drop of resin.

7. (Amended) The electronic circuit of claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive printing of a pattern, of a text or of a code.

REMARKS

In response to the Office Action mailed October 31, 2002, the Applicant respectfully requests reconsideration. To further the prosecution of the application, amendments are made in the claims and the following remarks are submitted. The application is believed to be in condition for allowance.

Claims 1-8 are pending in this application.

Specification

In paragraph 3 of the Office Action, the Examiner states that the application does not contain an Abstract of the disclosure. The Applicant respectfully disagrees, and directs the Examiner's attention to page 8 of the application, where the Abstract resides.